

注記
NOTES:

1.材質
MATERIAL
ハウジング:液晶ポリマー(LCP)、ナチュラル(白)、ガラス充填、UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER(LCP), NATURAL(WHITE)
GLASS FILLED, UL94V-0
アクチュエータ:ポリフェニレンサルファイド(PPS)、黒色、ガラス充填、UL94V-0
ACTUATOR: POLYPHENYLENE SULFIDE(PPS), BLACK
GLASS FILLED, UL94V-0
ターミナル:銅合金(t=0.12)
TERMINAL: COPPER ALLOY(t=0.12)
金具:リン青銅(t=0.12)
NAIL: PHOS-BRO(t=0.12)

2.めっき仕様
PLATING
ターミナル
TERMINAL
接点部:金めっき 0.1μm以上
CONTACT AREA: GOLD 0.1 MICROMETER MINIMUM.
半田付け部:金めっき
SOLDER TAIL AREA: GOLD
下地めっき:ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM.
金具
NAIL
錫めっき 1.0μm以上
TIN PLATING 1.0 MICROMETER MINIMUM.
下地めっき:ニッケル 1.0μm以上
UNDER PLATING: NICKEL 1.0 MICROMETER MINIMUM.

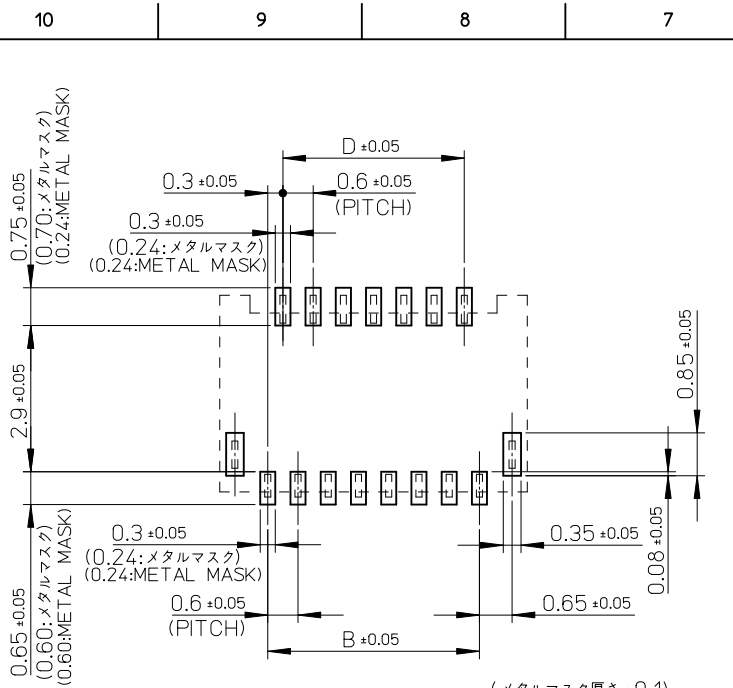
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

0.208	21.6	23.5	22.2	24.1	503425-7591	75
0.171	17.4	19.3	18.0	19.9	503425-6191	61
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS

CONNECTOR SERIES No. 503425-**11

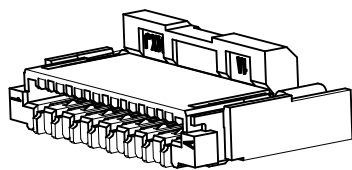
RELEASED EC NO.: J2010-2422 DRW: KUSATO 2009/04/28 CHK: HSHIMOYAMA 2010/05/28 APPR: KMORIKAWA 2010/05/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 20:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY KUSATO		DATE 2008/11/14		TITLE 0.3 FPC CONN. BACK FLIP HOUSING ASSY
	10 OVER 30 UNDER	±0.25	CHECKED BY HSHIMOYAMA		DATE 2008/11/14		
	30 OVER	±0.3	APPROVED BY HHRATA		DATE 2008/11/14		
	ANGULAR ±1 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-503425-001		SHEET NO. 1 OF 2
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



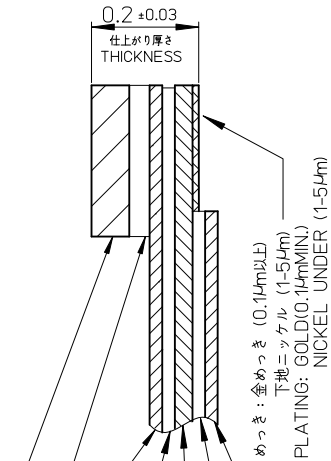
(メタルマスク厚さ:0.1)
(METAL MASK THICKNESS:0.1)

推奨基板寸法

RECOMMENDED P.W.B. PATTERN LAYOUT

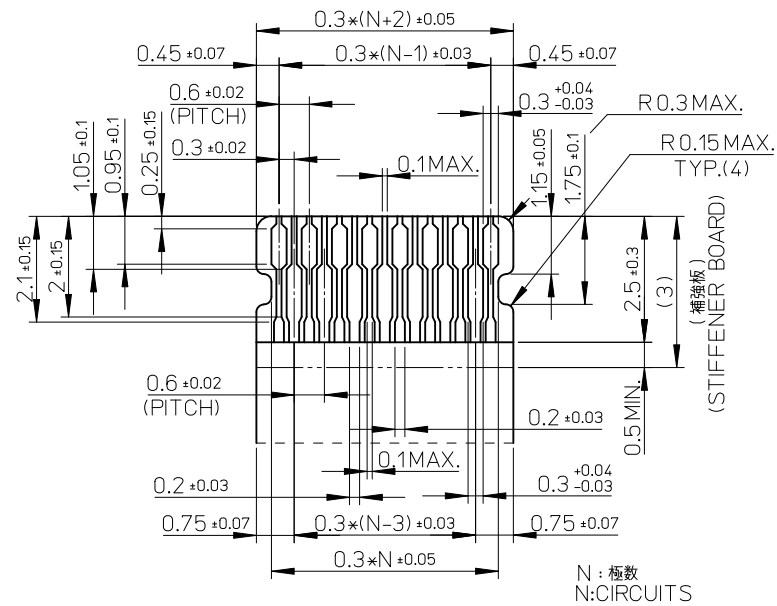


ISO VIEW (参考)



- 補強板: ポリイミド REINFORCE BOARD: POLYIMIDE
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- ベースフィルム: ポリイミド (25µm) BASE FILM: POLYIMIDE(25µm)
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- 導体部: 銅箔 (35µm) CONDUCTOR: COPPER FOIL (35µm)
- 熱硬化接着剤 THERMOSETTING ADHESIVE
- カバーレイ: ポリイミド (25µm) COVER FILM: POLYIMIDE(25µm)

FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION

(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:

- 抜き方向は、導体側から補強板側を推奨致します。
- 補強フィルム材質は、ポリイミドを推奨致します。
- 接着剤は熱硬化接着剤を推奨致します。
- 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC:

- RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
- RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
- PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE
CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

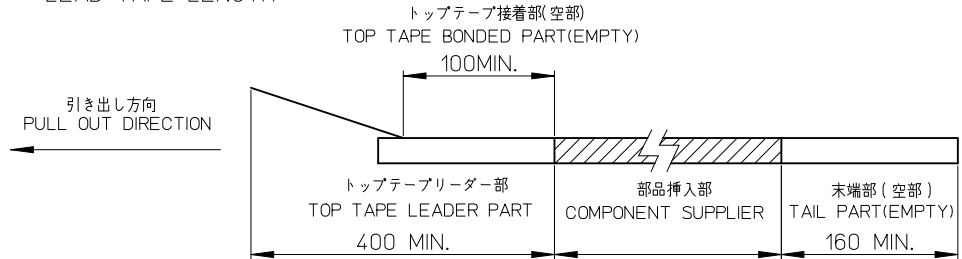
SEE SHEET 1 EC NO: J2010-2422 DRWN: KUSATO 2009/04/28 CHKD: HSHIMOYAMA 2010/05/28 APPR: KMORIKAWA 2010/05/31	DESCRIPTION REV: 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE	0.3 FPC CONN. BACK FLIP HOUSING ASSY			
		10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE	MOLEX INCORPORATED				
		30 OVER	± 0.3	APPROVED BY	DATE					
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-503425-001		2 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SIZE A3								

注記)
NOTES

1. 製品番号503425-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 503425-**11 DETAIL DIMENSIONS,
SEE SALES DRAWING FOR CONNECTOR.

2. 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL

3. リードテープ長さ
LEAD TAPE LENGTH



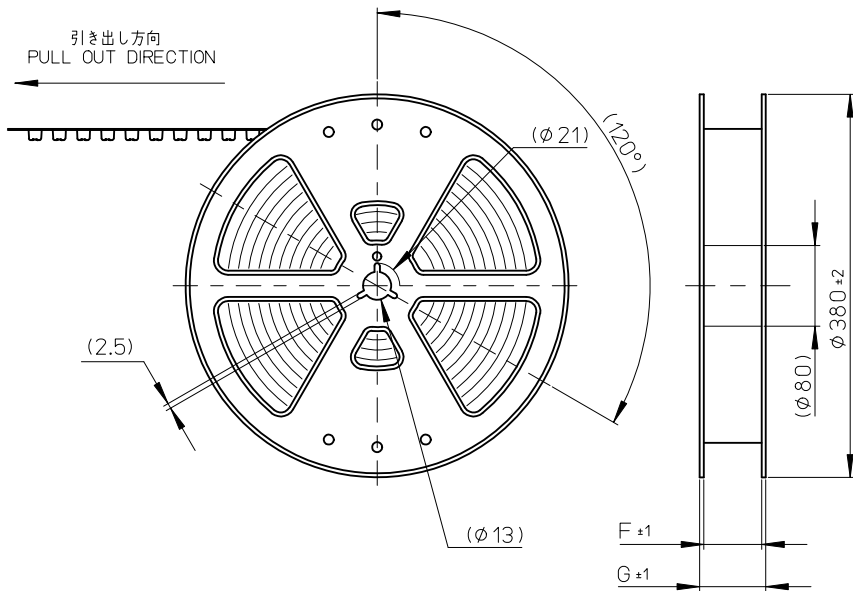
4. カバーテープの剥離強度については、IEC60286-3に準拠
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.

5. 材料

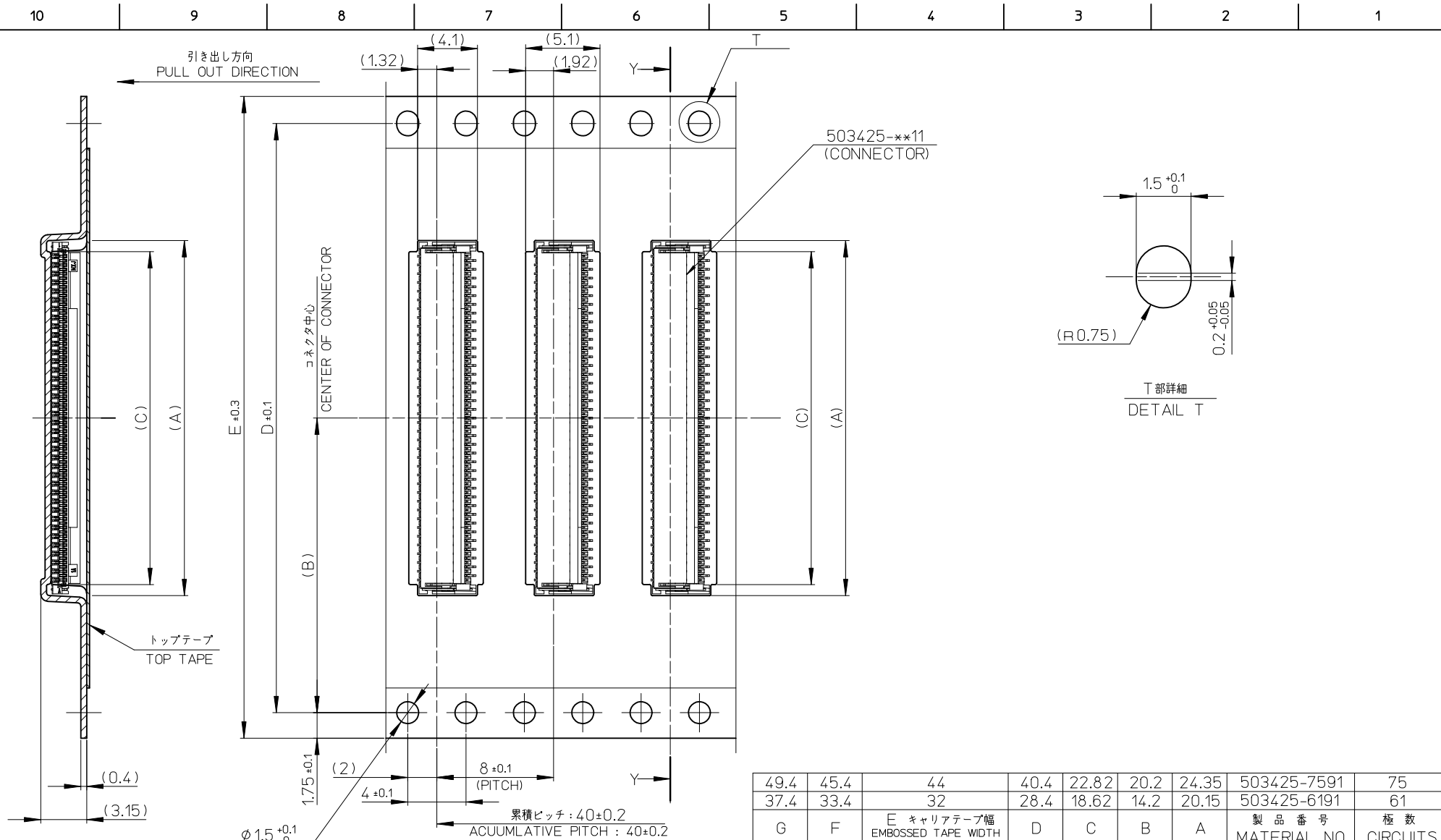
MATERIAL

キャリアテープ: ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ: PET, PE, PEF
TOP TAPE : PET, PE, PEF
リール: ポリスチレン
REEL: POLYSTYLENE

6. ELV及びRoHS適合品
ELV AND LoHS COMPLIANT



RELEASED EC NO.: J2010-2422 DRW: KUSATO 2008/11/19 CHK: HSHIMOYAMA 2010/05/28 APP: KMORIKAWA 2010/05/31	DESCRIPTION REV: O	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	\pm ---	DRAWN BY KUSATO	DATE 2008/11/19	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (503425-**11 SERIES) MOLEX INCORPORATED				
		10 OVER 30 UNDER	\pm ---	CHECKED BY HSHIMOYAMA	DATE 2008/11/19					
		30 OVER	\pm ---	APPROVED BY HHRATA	DATE 2008/11/19					
		ANGULAR $\pm 1^\circ$		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1 OF 2		DOCUMENT NO. SD-503425-002		SHEET NO. 1 OF 2
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



49.4	45.4	44	40.4	22.82	20.2	24.35	503425-7591	75	
37.4	33.4	32	28.4	18.62	14.2	20.15	503425-6191	61	
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH		D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

断面 Y-Y
SECTION Y-Y

SEE SHEET 1 OF 2 EC NO: J2010-2422 DRWN: KUSATO 2008/11/27 CH'KD: HSHIMUYAMA 2010/05/28 APPR: KMORI/KAWA 2010/05/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY KUSATO	DATE 2008/11/19	TITLE 0.3 FPC CONN. BACK FLIP TAPING PACKAGE (503425-**11 SERIES)			
	10 OVER 30 UNDER	± ---	CHECKED BY HSHIMUYAMA	DATE 2008/11/19	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY HHIRATA	DATE 2008/11/19				
ANGULAR ±1 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-503425-002		2 OF 2		
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						